

HOSTAFORM® C 9021 TF XAP®2

Tribological; low Emission

Chemical abbreviation according to ISO 1043-1: POM Molding compound ISO 29988- POM-K, M-GNS, 2-2 POM copolymer Injection molding type, modified with PTFE; good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation; for sliding combinations with very low coefficient of friction. Reduced emission grade. Emissions according to VDA 275 < 5 mg/kg Burning rate ISO 3795 and FMVSS 302 < 100 mm/min for a thickness more than 1 mm. Ranges of applications: For sliding combinations with very low coefficient of friction. FMVSS = Federal Motor Vehicle Safety Standard (USA)

Product information

Part Marking Code	POM		ISO 11469
Rheological properties			
Melt volume-flow rate	6	cm ³ /10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	
Moulding shrinkage, parallel	2.0	%	ISO 294-4, 2577
Moulding shrinkage, normal	1.7	%	ISO 294-4, 2577
Typical mechanical properties			
Tensile Modulus	2350	MPa	ISO 527-1/-2
Yield stress, 50mm/min	50	MPa	ISO 527-1/-2
Yield strain, 50mm/min	10	%	ISO 527-1/-2
Nominal strain at break	16	%	ISO 527-1/-2
Flexural Modulus		MPa	ISO 178
Tensile creep modulus, 1h		MPa	ISO 899-1
Tensile creep modulus, 1000h		MPa	ISO 899-1
Charpy impact strength, 23°C		kJ/m²	ISO 179/1eU
Charpy impact strength, -30°C		kJ/m²	ISO 179/1eU
Charpy notched impact strength, 23°C		kJ/m²	ISO 179/1eA
Charpy notched impact strength, -30 °C		kJ/m²	ISO 179/1eA
Ball indentation hardness, H 358/30	120	MPa	ISO 2039-1
Thermal properties			
Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Temp. of deflection under load, 1.8 MPa	98	°C	ISO 75-1/-2
Vicat softening temperature, 50°C/h, 50N	145	°C	ISO 306
Coeff. of linear therm. expansion, parallel	110	E-6/K	ISO 11359-1/-2
Electrical properties			
Relative permittivity, 100Hz	3.7		IEC 62631-2-1
Relative permittivity, 1MHz	3.7		IEC 62631-2-1
Dissipation factor, 100Hz		E-4	IEC 62631-2-1
Dissipation factor, 1MHz		E-4	IEC 62631-2-1

Printed: 2023-08-07 Page: 1 of 3

Revised: 2023-05-26 Source: Celanese Materials Database



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Volume resistivity	1E12 Ohm.m	IEC 62631-3-1
Surface resistivity	1E14 Ohm	IEC 62631-3-2
Electric strength	33 kV/mm	IEC 60243-1
Comparative tracking index	PLC 0 PLC	UL 746A

Other properties

Humidity absorption, 2mm	0.2 %	Sim. to ISO 62
Water absorption, 2mm	0.65 %	Sim. to ISO 62
Density	1510 kg/m ³	ISO 1183

Injection

Drying Temperature	100 - 120 °C
Drying Time, Dehumidified Dryer	3 - 4 h
Processing Moisture Content	0.15 %
Screw tangential speed	0.2 - 0.21 m/s
Max. mould temperature	80 - 120 °C
Back pressure	2 MPa
Injection speed	slow

Characteristics

Additives Release agent

Processing Texts

Pre-drying It is normally not necessary to dry HOSTAFORM. However, should there be

surface moisture (condensate) on the molding compound as a result of incorrect storage, drying is required. A circulating air drying cabinet can be used for this

purpose.

Longer pre-drying times/storage The product can then be stored in standard conditions until processed.

Other Approvals

Other Approvals

OEM	Specification	Additional Information
Mercedes-Benz Group (Daimler)	DBL 5404	BQF
Mercedes-Benz Group (Daimler)	DBL 5410	

Printed: 2023-08-07 Page: 2 of 3

Revised: 2023-05-26 Source: Celanese Materials Database



HOSTAFORM® C 9021 TF XAP®2

Printed: 2023-08-07 Page: 3 of 3

Revised: 2023-05-26 Source: Celanese Materials Database

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